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Symposium Program

November 9, 2015 (Monday)

Room A (Science Hall)

13:00-15:00 Session 1: On-board Optics

Chairpersons: Hidetoshi Numata (IBM Research-Tokyo), Jonas Weiss (IBM Research - Zurich)

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Chairpersons: Hideyuki Nasu (Furukawa Electric Co., Ltd.), Ulrich Keil (FCI Deutschland GmbH)

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Motoaki Tani and Taisuke Iwai
(Fujitsu Laboratories, Ltd.)*